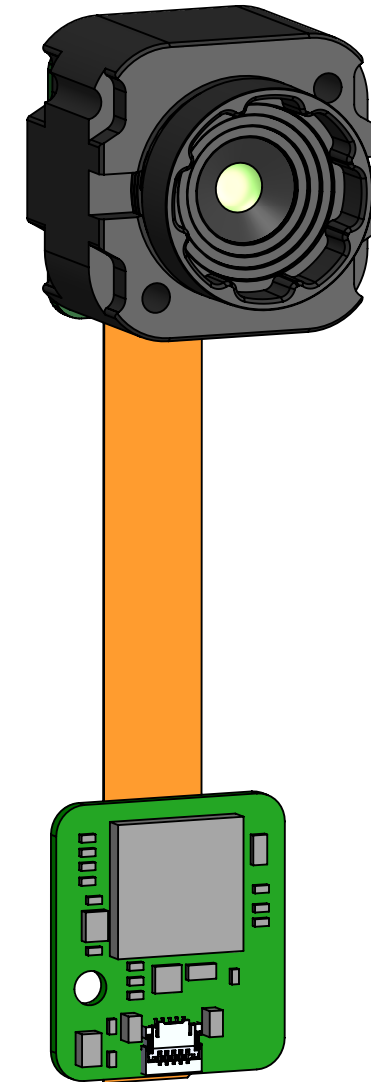
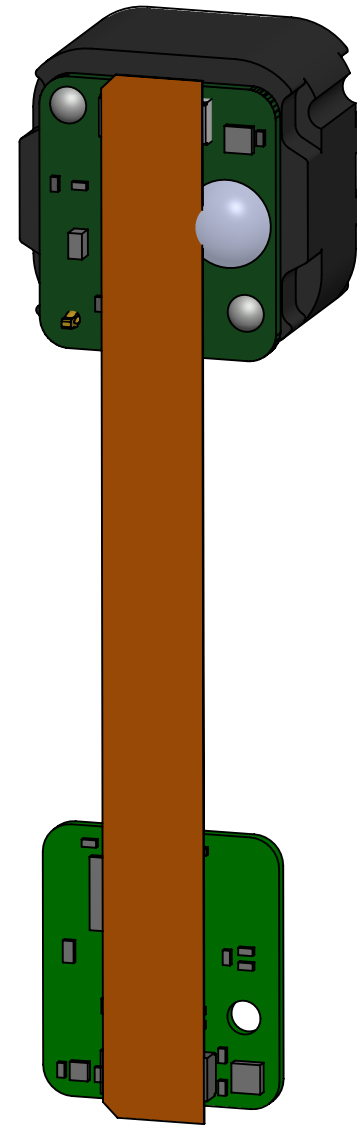
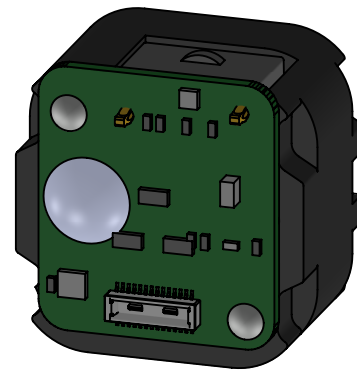
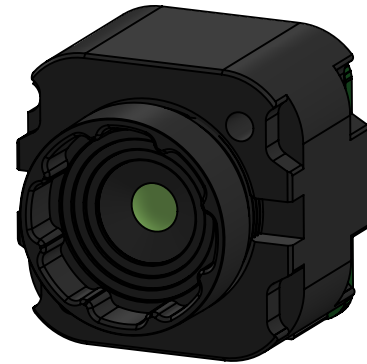


THIS DRAWING COVERS
THE FOLLOWING SKUS:

- C2*4*
- C3*4*
- S2*4*
- S3*4*

NO COPROCESSOR BOARD

"P" OPTION WITH COPROCESSOR BOARD



NOTES:

1. SEE 3D CAD FILE FOR FULL GEOMETRY.

2. KEEPOUT FOR SHUTTER CLEARANCE.

3. LENS ADHESIVE DOES NOT EXTEND ABOVE FRONT FACE.

2. THIS DESIGN IS CAPABLE OF BEING IP67 WHEN USED WITH APPROPRIATE SEALING DESIGN. SEE MOSAIC DATASHEET.

5. ADHESIVE BUMP PRESENT ON <9Hz CORES.

3. COPROCESSOR BOARD AND FLEX INCLUDED WITH "P" OPTION CORES.

MATERIAL	SEE NOTES	DRAWN	DLM	27MAR2019
FINISH	SEE NOTES	APPR.		
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MM (IN) IN ACCORDANCE WITH ASME Y14.5-2009		THIRD ANGLE PROJECTION		
GENERAL TOLERANCES 0.5 TO 6 ±0.1 [.004] > 6 TO 30 ±0.2 [.008] > 30 TO 120 ±0.2 [.008] > 120 TO 400 ±0.3 [.012] ANGLES ±1°		THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF SEEK THERMAL. ANY REPRODUCTION IN PART OR AS A WHOLE WITHOUT WRITTEN PERMISSION IS PROHIBITED.		



TITLE: DOC, INTERFACE CONTROL
DRAWING, MECH, 4.0MM MOSAIC

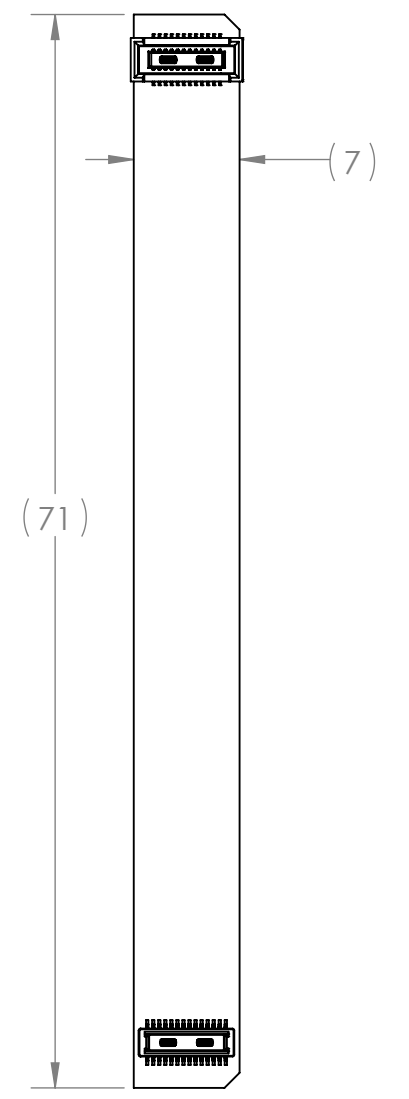
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SCALE: 2:1 SHEET 1 OF 2

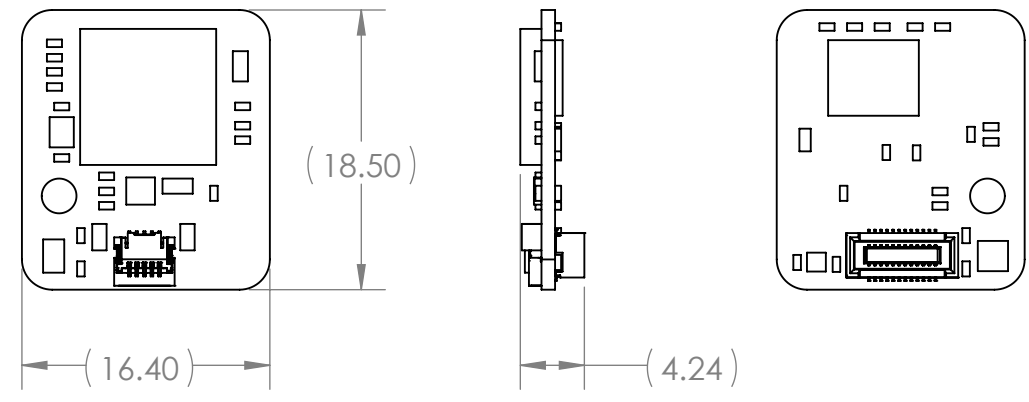
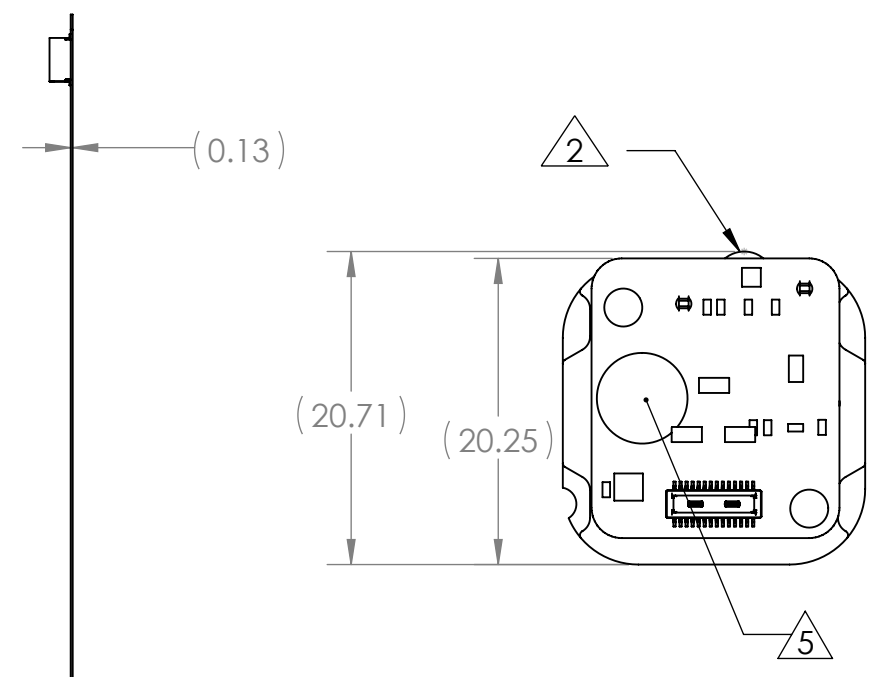
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D
C
B
A

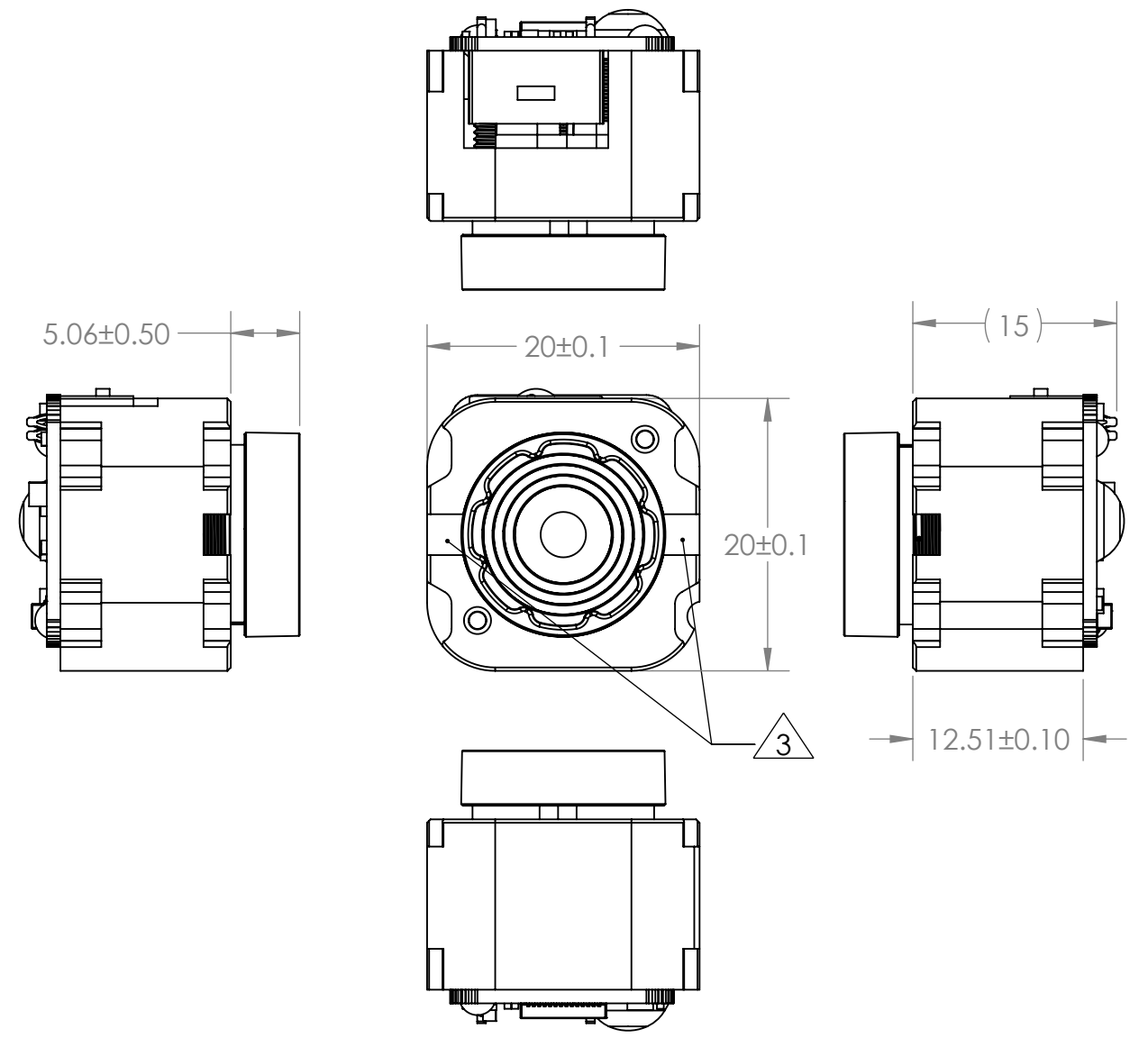
D
C
B
A



FLEX CABLE



COPROCESSOR BOARD



THERMAL IMAGING CORE

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thermal

TITLE: DOC, INTERFACE CONTROL
DRAWING, MECH, 4.0MM MOSAIC

SIZE B	DWG. NO. DOC_243	REV 3
SCALE: 2:1		SHEET 2 OF 2

8 7 6 5 4 3 2 1